TEXAS INSTRUMENTS 12500 TI Boulevard, MS 8640, Dallas, Texas 75243

Notification# 20190129002.0
Datasheet for MSP430FR4131-MSP430FR4133
Information Only

Date: January 30, 2019
To: MOUSER PCN

Dear Customer:

This is an information-only announcement of a change to the datasheet for a device that is currently offered by Texas Instruments.

The changes discussed within this notification are for your information only.

Any negotiated alternative change requirements will be provided via the customer's defined process. Customers with previously negotiated, special requirements will be handled separately. Any inquiries should be directed to your local Field Sales Representative.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

Information Only
Attachments

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
MSP430FR4131IG48	null
MSP430FR4131IG56	null
MSP430FR4132IG48	null
MSP430FR4132IG56	null
MSP430FR4132IPMR	null
MSP430FR4133IG48	null
MSP430FR4133IG48R	null
MSP430FR4133IG56	null
MSP430FR4133IG56R	null
MSP430FR4133IPM	null
MSP430FR4133IPMR	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20190129002.0	**PCN Date:**	January 30, 2019
Title:	Datasheet for MSP430FR4131-MSP430FR4133		
Customer Contact:	PCN Manager	**Dept:**	Quality Services

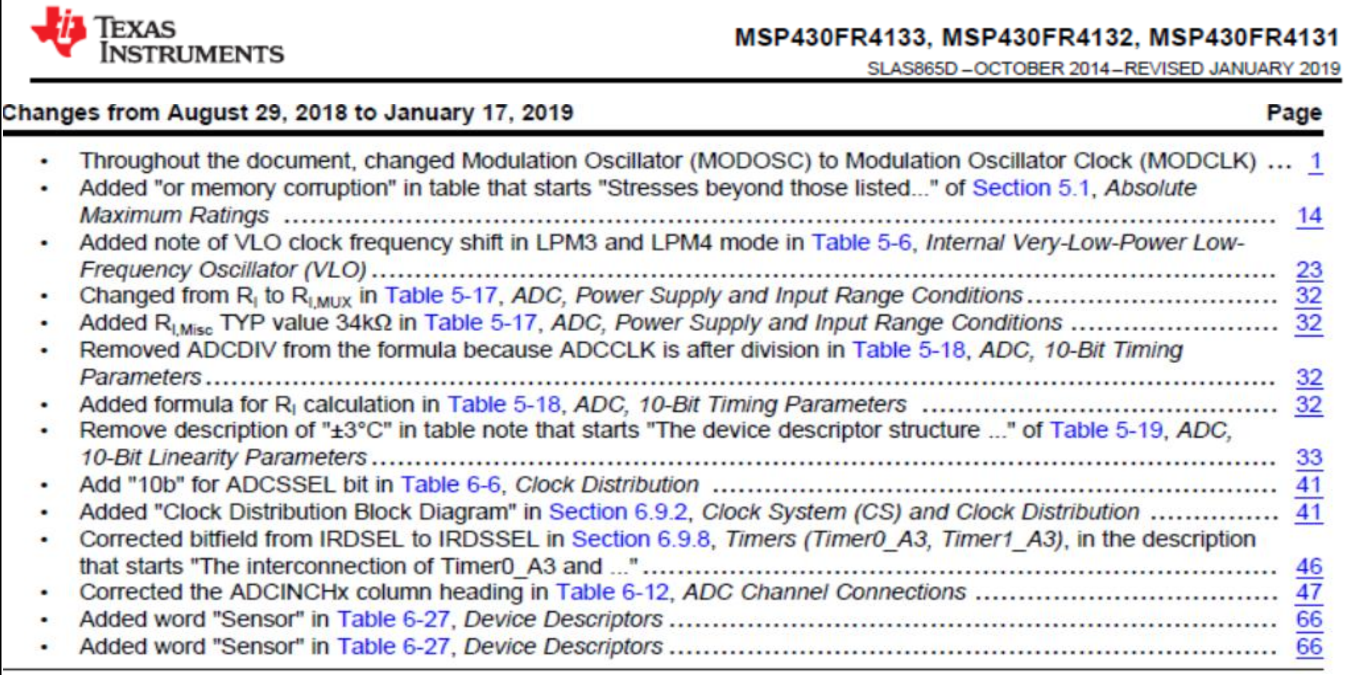
Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☒	Data Sheet	☐	Wafer Bump Material
☐	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification.
The product datasheet(s) is being updated as summarized below.
The following change history provides further details.



MSP430FR4133, MSP430FR4132, MSP430FR4131

SLAS865D –OCTOBER 2014–REVISED JANUARY 2019

Changes from August 29, 2018 to January 17, 2019 **Page**

- Throughout the document, changed Modulation Oscillator (MODOSC) to Modulation Oscillator Clock (MODCLK) ... 1
- Added "or memory corruption" in table that starts "Stresses beyond those listed..." of Section 5.1, *Absolute Maximum Ratings* ... 14
- Added note of VLO clock frequency shift in LPM3 and LPM4 mode in Table 5-6, *Internal Very-Low-Power Low-Frequency Oscillator (VLO)* ... 23
- Changed from R_I to $R_{I,MUX}$ in Table 5-17, *ADC, Power Supply and Input Range Conditions* ... 32
- Added $R_{I,Misc}$ TYP value 34kΩ in Table 5-17, *ADC, Power Supply and Input Range Conditions* ... 32
- Removed ADCDIV from the formula because ADCCLK is after division in Table 5-18, *ADC, 10-Bit Timing Parameters* ... 32
- Added formula for R_I calculation in Table 5-18, *ADC, 10-Bit Timing Parameters* ... 32
- Remove description of "±3°C" in table note that starts "The device descriptor structure ..." of Table 5-19, *ADC, 10-Bit Linearity Parameters* ... 33
- Add "10b" for ADCSSEL bit in Table 6-6, *Clock Distribution* ... 41
- Added "Clock Distribution Block Diagram" in Section 6.9.2, *Clock System (CS) and Clock Distribution* ... 41
- Corrected bitfield from IRDSEL to IRDSSEL in Section 6.9.8, *Timers (Timer0_A3, Timer1_A3)*, in the description that starts "The interconnection of Timer0_A3 and ..." ... 46
- Corrected the ADCINCHx column heading in Table 6-12, *ADC Channel Connections* ... 47
- Added word "Sensor" in Table 6-27, *Device Descriptors* ... 66
- Added word "Sensor" in Table 6-27, *Device Descriptors* ... 66

The datasheet number will be changing.

Device Family	Change From:	Change To:
MSP430FR4133, MSP430FR4132, MSP430FR4131	SLAS865C	SLAS865D

These changes may be reviewed at the datasheet links provided.

http://www.ti.com/product/MSP430FR4131

Reason for Change:

To accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

MSP430FR4131IG48	MSP430FR4131IG48R	MSP430FR4131IG56	MSP430FR4131IG56R
MSP430FR4131IPMR	MSP430FR4132IG48	MSP430FR4132IG48R	MSP430FR4132IG56
MSP430FR4132IG56R	MSP430FR4132IPMR	MSP430FR4133IG48	MSP430FR4133IG48R
MSP430FR4133IG56	MSP430FR4133IG56R	MSP430FR4133IPM	MSP430FR4133IPMR

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	**E-Mail**
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com